



USB3370

Enhanced Single Supply Hi-Speed USB ULPI Transceiver



PRODUCT FEATURES

Data Brief

- USB-IF Battery Charging 1.1 Specification Compliant
- Link Power Management (LPM) Specification Compliant
- Integrated ESD protection circuits
 - Up to ± 25 kV IEC Air Discharge without external devices
- External VBUS Fault Indicator Input Pin
- Over-Voltage Protection circuit (OVP) protects the VBUS pin from continuous DC voltages up to 30V
- SMSC RapidCharge Anywhere™ Provides:
 - 3-times the charging current through a USB port over traditional solutions
 - USB-IF Battery Charging 1.1 compliance to any portable device
 - Charging current up to 1.5Amps via compatible USB host or dedicated charger
 - Dedicated Charging Port (DCP), Charging (CDP) & Standard (SDP) Downstream Port support
- flexPWR® Technology
 - Extremely low current design ideal for battery powered applications
 - “Sleep” mode tri-states all ULPI pins and places the part in a low current state
 - 1.8V to 3.3V IO Voltage
- Single Power Supply Operation
 - Integrated 1.8V regulator
 - Integrated 3.3V regulator
 - 100mV dropout voltage
- PHYBoost
 - Programmable USB transceiver drive strength for recovering signal integrity
- VariSense™
 - Programmable USB receiver sensitivity
- “Wrapper-less” design for optimal timing performance and design ease
 - Low Latency Hi-Speed Receiver (43 Hi-Speed clocks Max) allows use of legacy UTMI Links with a ULPI bridge
- External Reference Clock operation available
 - ULPI Clock Input Mode (60MHz sourced by Link)
 - 0 to 3.6V input drive tolerant
 - Able to accept “noisy” clock sources as reference to internal, low-jitter PLL
 - Crystal support available
- Smart detection circuits allow identification of USB charger, headset, or data cable insertion
- Includes full support for the optional On-The-Go (OTG) protocol detailed in the On-The-Go Supplement Revision 2.0 specification
- Supports the OTG Host Negotiation Protocol (HNP) and Session Request Protocol (SRP)
- UART mode for non-USB serial data transfers
- Internal 5V cable short-circuit protection of ID, DP and DM lines to VBUS or ground
- Industrial Operating Temperature -40°C to $+85^{\circ}\text{C}$
- 32-pin, QFN lead-free RoHS Compliant package (5 x 5 x 0.90 mm height)

Applications

The USB3370 is the solution of choice for any application where a Hi-Speed USB connection is desired and when board space, power, and interface pins must be minimized.

- Cell Phones
- PDAs
- MP3 Players
- GPS Personal Navigation
- Scanners
- External Hard Drives
- Digital Still and Video Cameras
- Portable Media Players
- Entertainment Devices
- Printers
- Set Top Boxes
- Video Record/Playback Systems
- IP and Video Phones
- Gaming Consoles

Order Number(s):

ORDER NUMBER	REFCLK FREQUENCY	PACKAGE TYPE	REEL SIZE
USB3370B-EZK-TR	19.2 MHz	32-Pin, QFN Lead-Free RoHS Compliant Package (tape and reel)	4,000 pieces

This product meets the halogen maximum concentration values per IEC61249-2-21
For RoHS compliance and environmental information, please visit www.smSC.com/rohs

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General Description

SMSC's USB3370 is a family of Hi-Speed USB 2.0 Transceivers that provide a physical layer (PHY) solution well-suited for portable electronic devices. Both commercial and industrial temperature applications are supported.

Several advanced features make the USB3370 the transceiver of choice by reducing both eBOM part count and printed circuit board (PCB) area. Outstanding ESD robustness eliminates the need for external ESD protection devices in typical applications. The internal Over-Voltage Protection circuit (OVP) protects the USB3370 from voltages up to 30V on the **VBUS** pin. By using a reference clock from the Link, the USB3370 removes the cost of a dedicated crystal reference from the design. The USB3370 includes integrated 3.3V and 1.8V regulators, making it possible to operate the device from a single power supply.

The USB3370 is optimized for use in portable applications where a low operating current and standby currents are essential. The USB3370 operates from a single supply and includes integrated regulators for its supplies. The USB3370 also supports the USB Link Power Management protocol (LPM) to further reduce USB operating currents.

The USB3370 also includes family is enabled with SMSC's RapidCharge Anywhere™ which supports USB-IF Battery Charging 1.1 for any portable device. RapidCharge Anywhere™ provides three times the charging current through a USB port over traditional solutions which translate up to 1.5Amps via compatible USB host or dedicated charger. In addition, this provides a complete USB charging ecosystem between device and host ports such as Dedicated Charging Port (DCP), Charging (CDP) and Standard (SDP) Downstream Ports.

The USB3370 meets all of the electrical requirements for a Hi-Speed USB Host, Device, or an On-the-Go (OTG) transceiver. In addition to the supporting USB signaling, the USB3370 also provides USB UART mode.

USB3370 uses the industry standard UTMI+ Low Pin Interface (ULPI) to connect the USB transceiver to the Link. ULPI uses a method of in-band signaling and status byte transfers between the Link and PHY to facilitate a USB session with only twelve pins.

The USB3370 uses SMSC's "wrapper-less" technology to implement the ULPI interface. This "wrapper-less" technology allows the PHY to achieve a low latency transmit and receive time. SMSC's low latency transceiver allows an existing UTMI Link to be reused by adding a UTMI to ULPI bridge. By adding a bridge to the ASIC the existing and proven UTMI Link IP can be reused.

Block Diagram

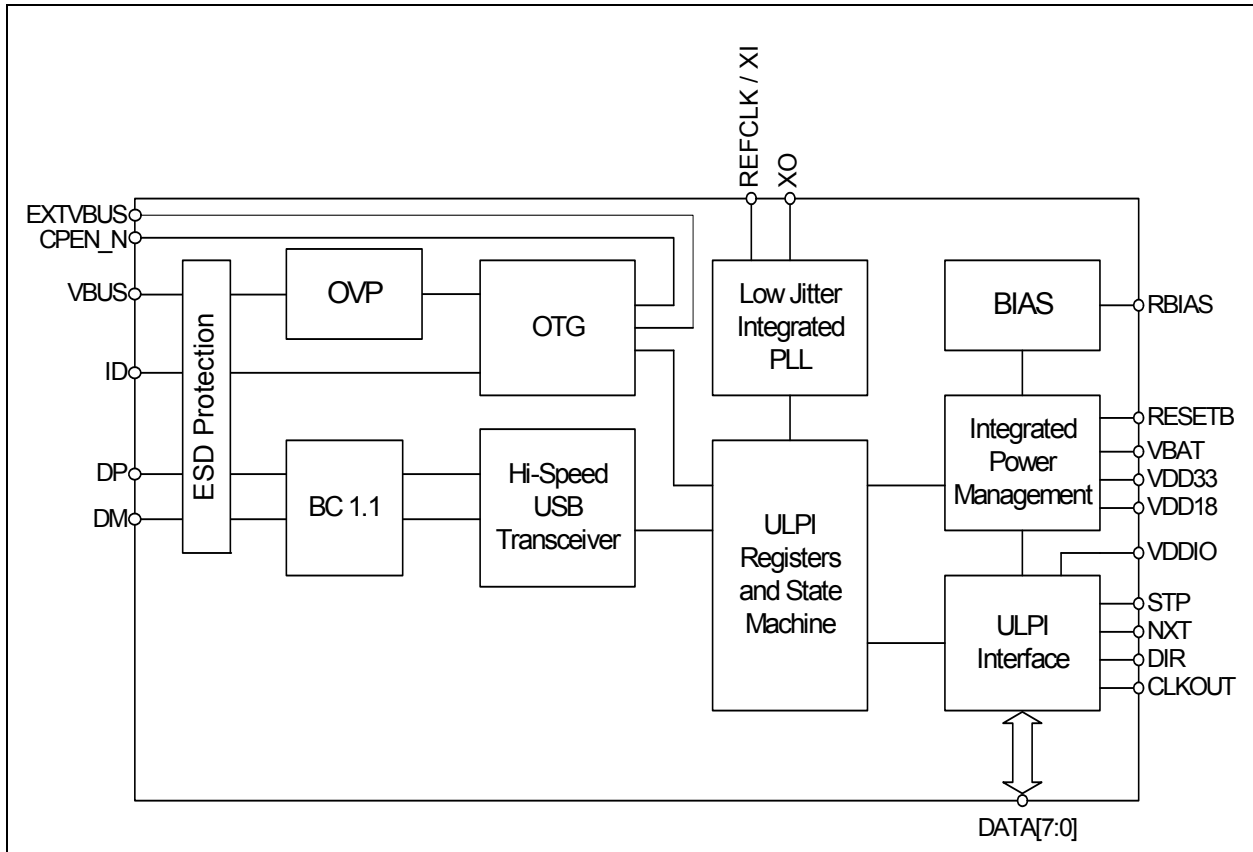


Figure 1 Block Diagram USB3370

Package Outline

Revision 1.0 (10-08-12)

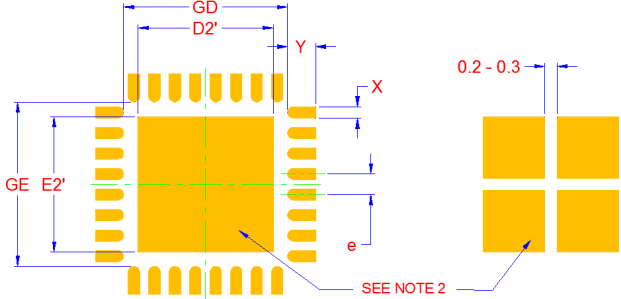
PRODUCT PREVIEW

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SMSC USB3370B

COMMON DIMENSIONS					
SYMBOL	MIN	NOM	MAX	NOTE	REMARK
A	0.70	0.85	1.00	-	OVERALL PACKAGE HEIGHT
A1	0	0.02	0.05	-	STANDOFF
A2	-	0.65	0.90	-	MOLD CAP THICKNESS
D/E	4.90	5.00	5.10	-	X/Y BODY SIZE
D1/E1	4.55	4.75	4.95	-	X/Y MOLD CAP SIZE
D2/E2	3.20	3.30	3.40	-	X/Y EXPOSED PAD SIZE
L	0.30	0.40	0.50	-	TERMINAL LENGTH
b	0.18	0.25	0.30	2	TERMINAL WIDTH
k	0.35	0.45	-	-	TERMINAL TO ePAD CLEARANCE
e	0.50 BSC		-	-	TERMINAL PITCH

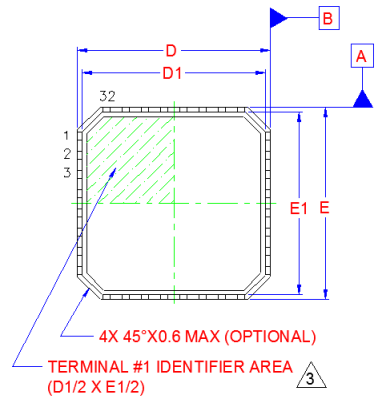
- NOTES:**
- ALL DIMENSIONS ARE IN MILLIMETERS.
 - DIMENSIONS "b" APPLIES TO PLATED TERMINALS AND IT IS MEASURED BETWEEN 0.15 AND 0.30 mm FROM THE TERMINAL TIP.
 - DETAILS OF TERMINAL #1 IDENTIFIER ARE OPTIONAL BUT MUST BE LOCATED WITHIN THE AREA INDICATED.



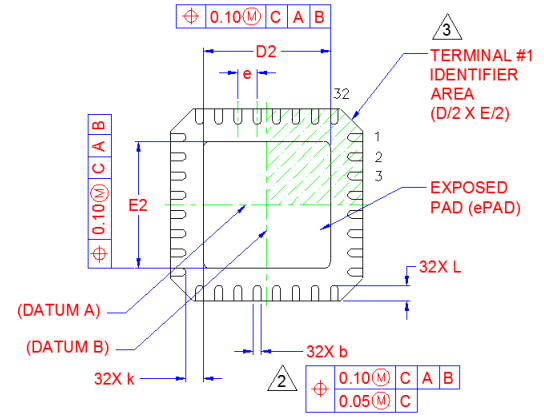
LAND PATTERN DIMENSIONS			
SYMBOL	MIN	NOM	MAX
GD/GE	4.00	-	4.10
D2'/E2'	3.10	-	3.30
X	-	0.24	0.28
Y	-	0.69	0.75
e	0.50		

- NOTES:**
- THE USER MAY MODIFY THE PCB LAND PATTERN DESIGN AND DIMENSIONS BASED ON THEIR EXPERIENCE AND/OR PROCESS CAPABILITY
 - EXPOSED SOLDERABLE COPPER AREA OF THE CENTER PAD CAN BE EITHER SOLID OR SEGMENTED
 - MAXIMUM THERMAL AND ELECTRICAL PACKAGE PERFORMANCE IS ACHIEVED WHEN AN ARRAY OF SOLID VIAS IS INCORPORATED IN THE CENTER LAND PATTERN

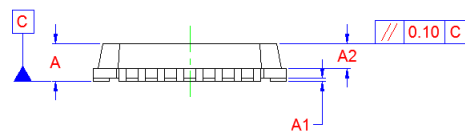
PCB LAND PATTERN



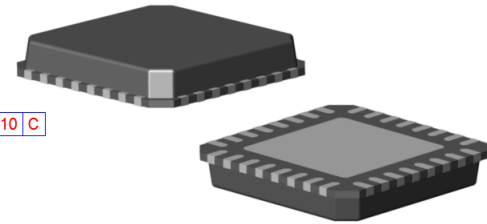
TOP VIEW



BOTTOM VIEW



SIDE VIEW



3-D VIEWS

Figure 2 USB3370 32-Pin QFN, 5x5mm Body, 0.5mm Pitch

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